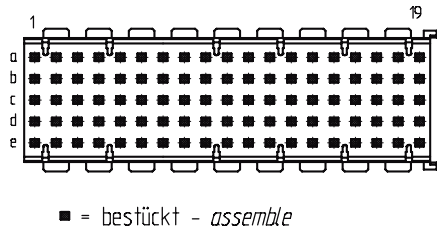


Bestückungsplan - *contact layout*



RoHS: 6/6

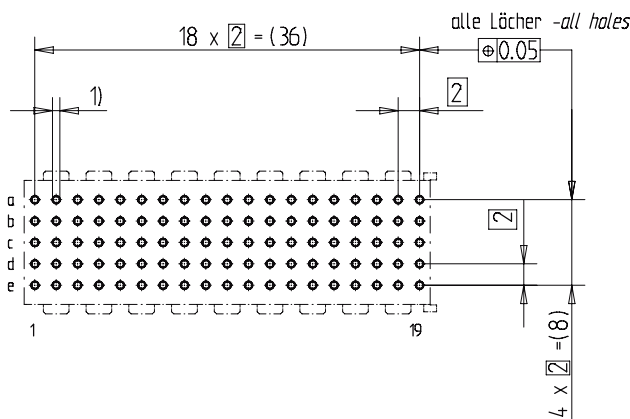
**Plating:**

Signal Contacts:

Termin. area: 2-3 µm Ni, 0,5-2 µm Sn

Mating area: 2-3 µm Ni, 0,65 µm Pd Ni with Au-Flash

Lochbild für Leiterplatte *Board hole pattern*  
(Bestückungsseite) *(Component mounting side)*



- 1)  $\varnothing 0,6 \pm 0,05$  Durchmesser des metallisierten Loches  
 $\varnothing 0,6 \pm 0,05$  Diameter of finished plated-through hole
- $\varnothing 0,7 \pm 0,02$  Bohrungsdurchmesser des Loches  
 $\varnothing 0,7 \pm 0,02$  Diameter of drilled hole

Schichtaufbau im metallisierten Loch  
siehe Zeichnung 114406

*Metal plating of plated-through hole  
see drawing 114406*

Fehlende Masse und Angaben nach IEC 61076-4-101  
*Missing information and dimensions per IEC 61076-4-101*

Consider protection memo from DIN 34	Information:	Tolerances	 All Dimensions in mm	Scale	2:1
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